

ABSTRACT

A method for attaching a semiconductor die to a leadframe is provided. Also provided are an improved semiconductor package, and a system for performing the method. The method includes applying an instant curing adhesive, such as a cyanoacrylate monomer or anaerobic adhesive, to the leadframe or die, and then polymerizing the adhesive at room temperature and ambient atmosphere, to form a cured adhesive layer between the die and lead frame. A catalyst can be applied to the leadframe, to the die or to the adhesive, to initiate polymerization. In addition, fillers can be added to the adhesive to improve various electrical and physical characteristics of the resultant adhesive layer. The system includes a dispensing mechanism for dispensing the instant curing adhesive on the leadframe or die, and a die attach mechanism for positioning and placing the die in contact with the dispensed adhesive.

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